

U.S. Patent Application Serial No. 10/660,745
Amendment filed March 3, 2006
Reply to OA dated October 7, 2005

AMENDMENTS TO THE SPECIFICATION:

Amend the specification as follows:

Amend the paragraph beginning at page 9, line 1, as follows:

The heat radiation shielding film forming coating liquid according to the present invention is characterized by being obtained by adding the heat radiation shielding component dispersion to an organic solvent to dissolve ~~its heat radiation shielding component~~ the polymer dispersant, and adding a binder component.

Amend the paragraph beginning at page 24, line 22, to page 25, line 7, as follows:

The heat radiation shielding film forming coating liquid according to the present invention may be obtained by adding the heat radiation shielding component dispersion to the organic solvent to dissolve ~~its heat radiation shielding component~~ the polymer dispersant and disperse the fine hexaboride particles uniformly in an organic solvent, and adding a binder component. As this organic solvent, any solvent may be selected as desired, as along as it is a solvent capable dissolving the polymer type dispersant used. It may include the alcohols, esters, ketones, ethers and aromatic compounds described previously.

Amend the paragraph beginning at page 27, line 12, as follows:

In the heat radiation shielding film forming coating liquid according to the present invention, it is obtained by adding the heat radiation shielding component dispersion to the organic solvent to

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dissolve its heat radiation shielding component the polymer dispersant, and adding the binder component. This makes it possible to obtain the heat radiation shielding film simply.